



#### 60V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on) max</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
60V	140m $\Omega$ @ V <sub>GS</sub> = 10V	2.3A
807	170m $\Omega$ @ V <sub>GS</sub> = 4.5V	2.1A

## Description

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

# Applications

- DC-DC Converters
- Power Management Functions
- Analog Switch

## **Features and Benefits**

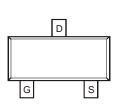
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

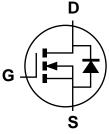
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.0072 grams (Approximate)



Top View



Pin Configuration



Equivalent Circuit

### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN6140L-7	SOT23	3,000/Tape & Reel
DMN6140L-13	SOT23	10,000/Tape & Reel

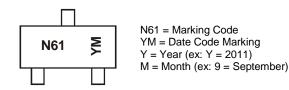
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



Date Code Key

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Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Y		Z		А	E	3	С		D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units		
Drain-Source Voltage			V <sub>DSS</sub>	60	V	
Gate-Source Voltage			V <sub>GSS</sub>	±20	V	
	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	1.6 1.2	A	
Continuous Drain Current (Note 5) $V_{GS}$ = 10V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	2.0 1.6		
	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	2.3 1.8	А	
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	2.9 2.3	А	
Maximum Continuous Body Diode Forward Currer	nt (Note 6)	Is	1.5	А		
Pulsed Drain Current (10µs pulse, duty cycle = 1%	5)	I <sub>DM</sub>	10	А		

# **Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	D	0.7	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.4	vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	183	°C/W	
Thermal Resistance, Sunction to Ambient (Note 5)	t<10s	R <sub>θJA</sub>	115	0/11	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	D	1.3	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	PD	0.8	vv	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	94		
Thermal Resistance, Sunction to Ambient (Note 0)	t<10s	$R_{ hetaJA}$	61	°C/W	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	39			
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)			1	r		-
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	1	μA	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Source Leakage	IGSS	—	—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1	—	3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	Р		92	140	mΩ	$V_{GS} = 10V, I_D = 1.8A$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		115	170	11122	$V_{GS} = 4.5V, I_D = 1.3A$
Forward Transfer Admittance	Y <sub>fs</sub>	—	2.2	_	S	$V_{DS} = 15V, I_D = 1.8A$
Diode Forward Voltage	V <sub>SD</sub>	—	0.75	1.0	V	$V_{GS} = 0V, I_{S} = 0.45A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	—	315	—		
Output Capacitance	Coss	_	18	—	pF	$V_{DS} = 40V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	—	16	—		
Gate Resistnace	R <sub>g</sub>	_	0.65	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	—	8.6	—		
Total Gate Charge (V <sub>GS</sub> = 5V)	Qg	—	4.1	—	nC	V 20V/ L 1.9A
Gate-Source Charge	Q <sub>gs</sub>	—	1.0	-	no	$V_{DS} = 30V, I_D = 1.8A$
Gate-Drain Charge	Q <sub>gd</sub>	—	1.7	-		
Turn-On Delay Time	t <sub>D(on)</sub>	_	2.6	—		
Turn-On Rise Time	tr	—	3.6	_	-	$V_{DS} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time	t <sub>D(off)</sub>	—	16.3	—	ns	$R_G = 6.0\Omega, I_D = 1.8A$
Turn-Off Fall Time	t <sub>f</sub>		2.7	_	]	
Reverse Recovery Time	t <sub>rr</sub>	—	16.8	—	ns	
Reverse Recovery Charge	Q <sub>rr</sub>		9.0	—	nC	I <sub>F</sub> = 1.8A, di/dt =100A/μs

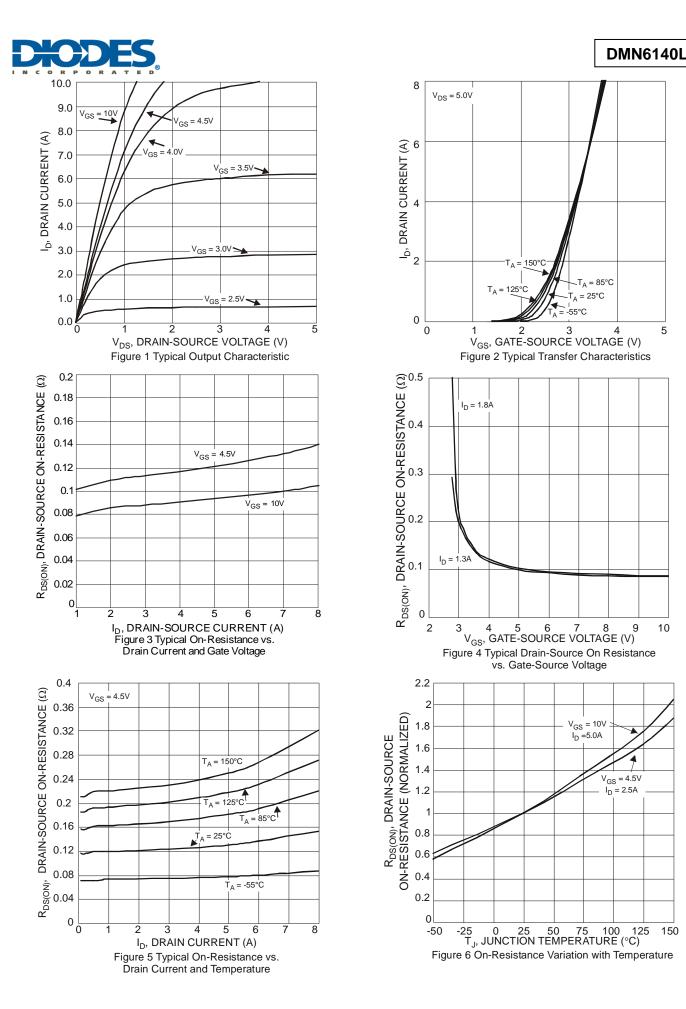
Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1in. square copper plate.

7 .Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to production testing.

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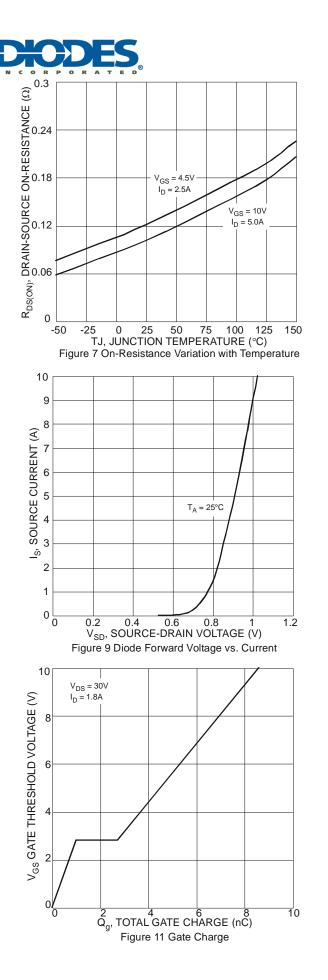
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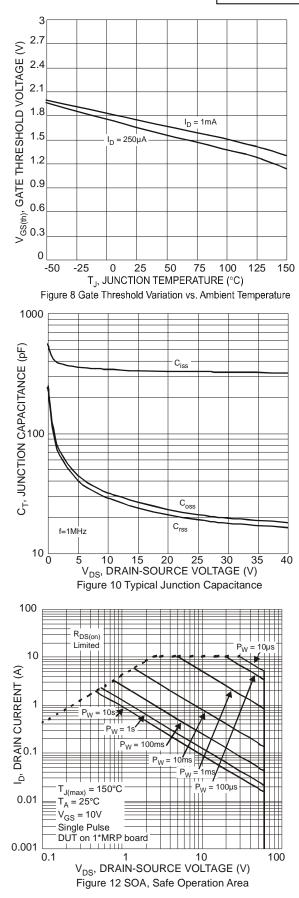
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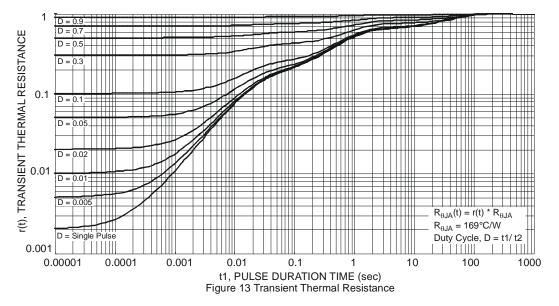
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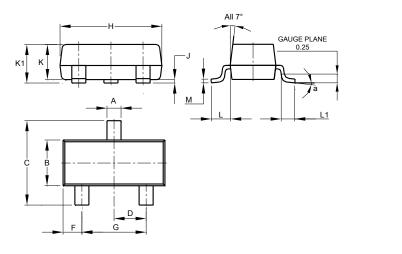






# **Package Outline Dimensions**

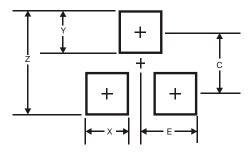
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SOT23							
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
н	2.80	3.00	2.90					
J	0.013	0.10	0.05					
ĸ	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
М	0.085	0.150	0.110					
α		8°						
All	Dimens	ions in	mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35



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